



## Material Content Data Sheet



Sales Product Name	SAF-XE167F-96F66L AC			Issued		29. August 2013		
MA#	MA001060244							
Package	PG-LQFP-144-4			Weight*		1469.89 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	40.856	2.78	2.78	27795	27795
leadframe	inorganic material	phosphorus	7723-14-0	0.126	0.01		86	
	non noble metal	zinc	7440-66-6	0.503	0.03		342	
	non noble metal	iron	7439-89-6	10.062	0.68		6845	
	non noble metal	copper	7440-50-8	408.558	27.80	28.52	277951	285224
wire	noble metal	gold	7440-57-5	5.975	0.41	0.41	4065	4065
encapsulation	organic material	carbon black	1333-86-4	4.909	0.33		3340	
	plastics	epoxy resin	-	132.537	9.02		90168	
	inorganic material	silicondioxide	60676-86-0	844.308	57.44	66.79	574401	667909
leadfinish	non noble metal	tin	7440-31-5	9.120	0.62	0.62	6204	6204
plating	noble metal	silver	7440-22-4	2.462	0.17	0.17	1675	1675
glue	plastics	epoxy resin	-	2.619	0.18		1782	
	noble metal	silver	7440-22-4	7.858	0.53	0.71	5346	7128
*deviation	< 10%	Sum in total:			100,00		1000000	

### Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

Company	Infineon Technologies AG
Address	81726 München
Internet	www.infineon.com